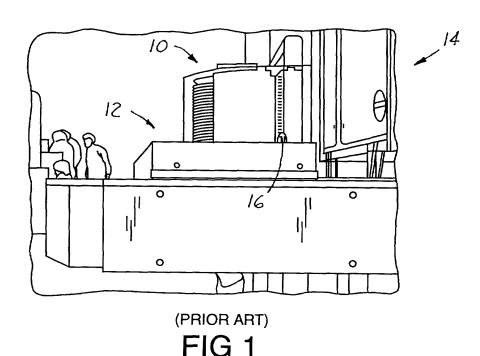
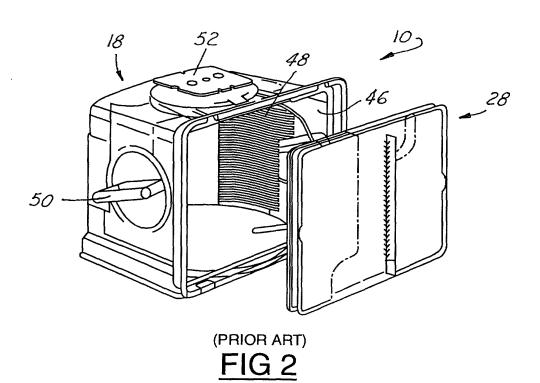
Inventor(s): Tseng, et al Serial No.: To Be Assigned
Filed: Herewith
For: Wafer Transport Pod With Linear Door Opening Mechanism
Attorney Docket No.: 67,200-674

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